

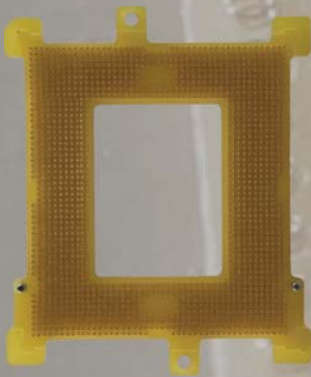


HIGH CONNECTION DENSITY, INC.

SuperSpring® Contact Element Specifications



HCD's SuperSpring® connector technology combines a high strength core material with a high conductivity shell to enable high density connectivity in a low-profile connector. SuperSpring™ contact elements are assembled by HCD into an FR-4 interposer and can be designed to virtually any custom array size.

For information on custom designed contact elements, please contact connector@hcdcorp.com.





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Type B: 1.0mm pitch and higher

	Type B16			Type B06			Type B12	
Minimum Pitch:	1.00	[40]		1.00	[40]		1.00	[40]
Free length:	1.52	[60]		1.02	[40]		1.02	[40]
Outside diameter:	0.53	[21]		0.53	[21]		0.53	[21]
Inside diameter:	0.38	[15]		0.38	[15]		0.38	[15]
Min. pad size on board:	0.46	[18]		0.66	[26]		0.66	[26]
Maximum travel:	0.72	[28]		0.25	[10]		0.15	[6]
Contact resistance:	80 mOhm			80 mOhm			60 mOhm	
Capacitance:	0.02 pF			0.02 pF			0.02 pF	
Inductance:	2.2 nH			1.8 nH			0.9 nH	
Bandwidth:	4.4 GHz			6 GHz			9 GHz	

Type C: 0.8mm pitch and higher

	Type C05			Type C01			Type C04	
Minimum Pitch:	0.80	[30]		0.80	[30]		0.80	[30]
Free length:	2.10	[83]		1.02	[40]		1.02	[40]
Outside diameter:	0.46	[18]		0.46	[18]		0.46	[18]
Inside diameter:	0.30	[12]		0.30	[12]		0.30	[12]
Min. pad size on board:	0.58	[23]		0.58	[23]		0.58	[23]
Maximum travel:	0.36	[14]		0.30	[12]		0.15	[6]
Contact resistance:	70 mOhm			70 mOhm			50 mOhm	
Capacitance:	0.06 pF			0.03 pF			0.03 pF	
Inductance:	2.0 nH			1.2 nH			0.6 nH	
Bandwidth:	4.5 GHz			8 GHz			10 GHz	

Type D: 0.5mm pitch and higher

	Type D05			Type D07			Type D11	
Minimum Pitch:	0.50	[20]		0.50	[20]		0.50	[20]
Free length:	2.10	[83]		1.02	[50]		2.03	[80]
Outside diameter:	0.33	[13]		0.30	[12]		0.30	[12]
Tip diameter:	0.22	[8]		0.20	[8]		0.22	[8]
Min. pad size on board:	0.31	[13]		0.31	[13]		0.31	[13]
Maximum travel:	0.36	[14]		0.25	[14]		0.43	[17]
Contact resistance:	60 mOhm			50 mOhm			80 mOhm	
Capacitance:	0.06 pF			0.03 pF			0.06 pF	
Inductance:	2.0 nH			1.54 nH			2.0 nH	
Bandwidth:	4.5 GHz			7.3 GHz			4.5 GHz	

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